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By: Marcia Wallenfels
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11/29/01
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Chris Macris
Serial No. : 09/927,314
Filed : August 10, 2001
For : HEAT DISSIPATING SILICON-ON-INSULATOR
STRUCTURES (CIP)

Art Unit :

2011 1741

Assistant Commissioner for Patents
Washington, D.C. 20231

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TC 1700
Parsons

INFORMATION DISCLOSURE STATEMENT

Dear Sir:

Enclosed is a list of prior art that may be relevant to the invention disclosed and claimed in the above-identified patent application. Copies of the cited references are enclosed.

Respectfully submitted,
JENSEN & PUNTIGAM, P.S.

Robert A. Jensen
Robert A. Jensen, #24,263

RAJ:mw

Enclosures: List of Prior Art
Postcard

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